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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

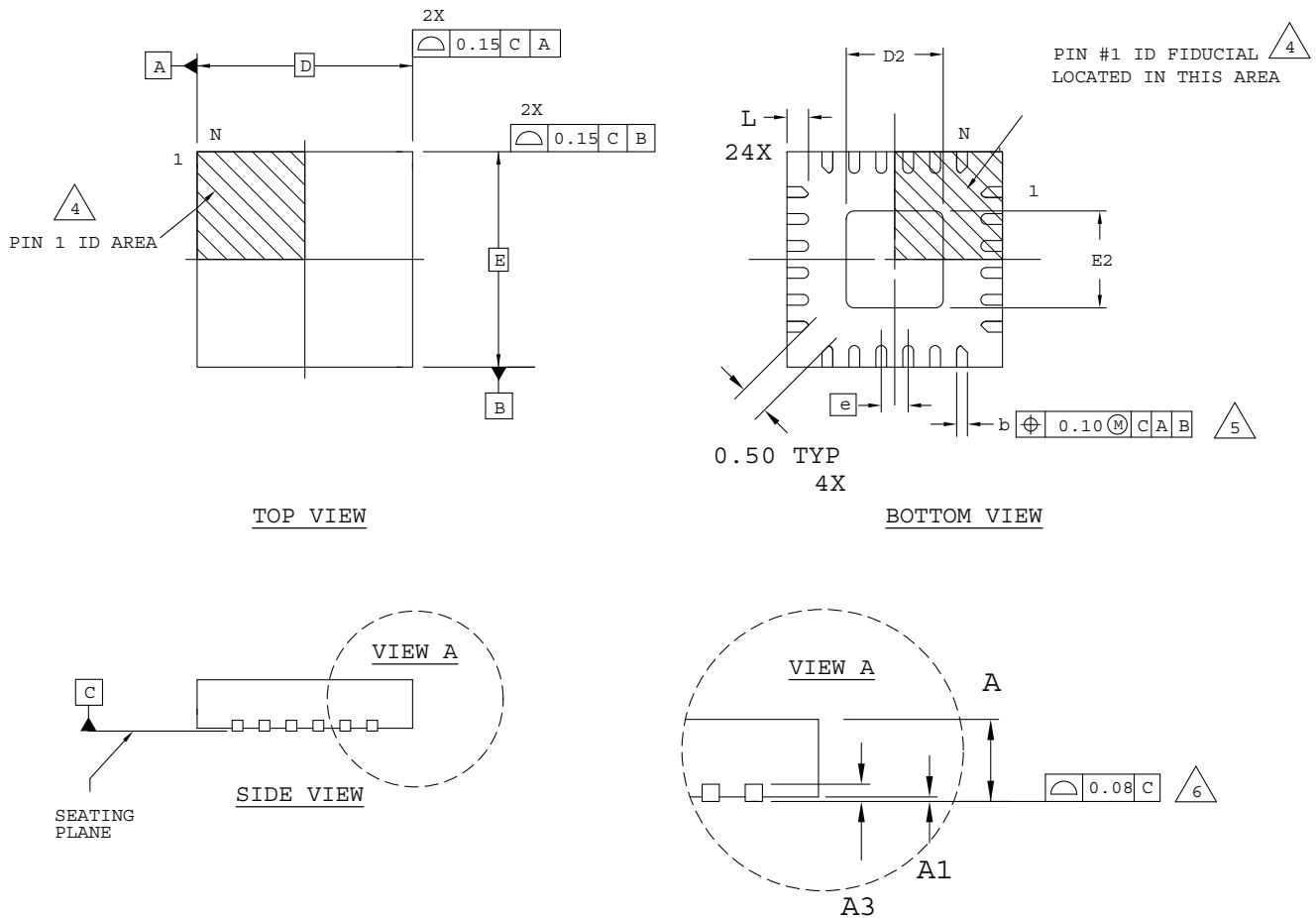
The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	32800
Total RAM Bits	434176
Number of I/O	496
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-FPBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec33e-4f672i


24-Pin QFNS Package


Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES
PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DRAWING CONFORMS TO JEDEC MO-220, VARIATION VGGD-9.

 EXACT SHAPE AND SIZE OF THIS
FEATURE IS OPTIONAL.

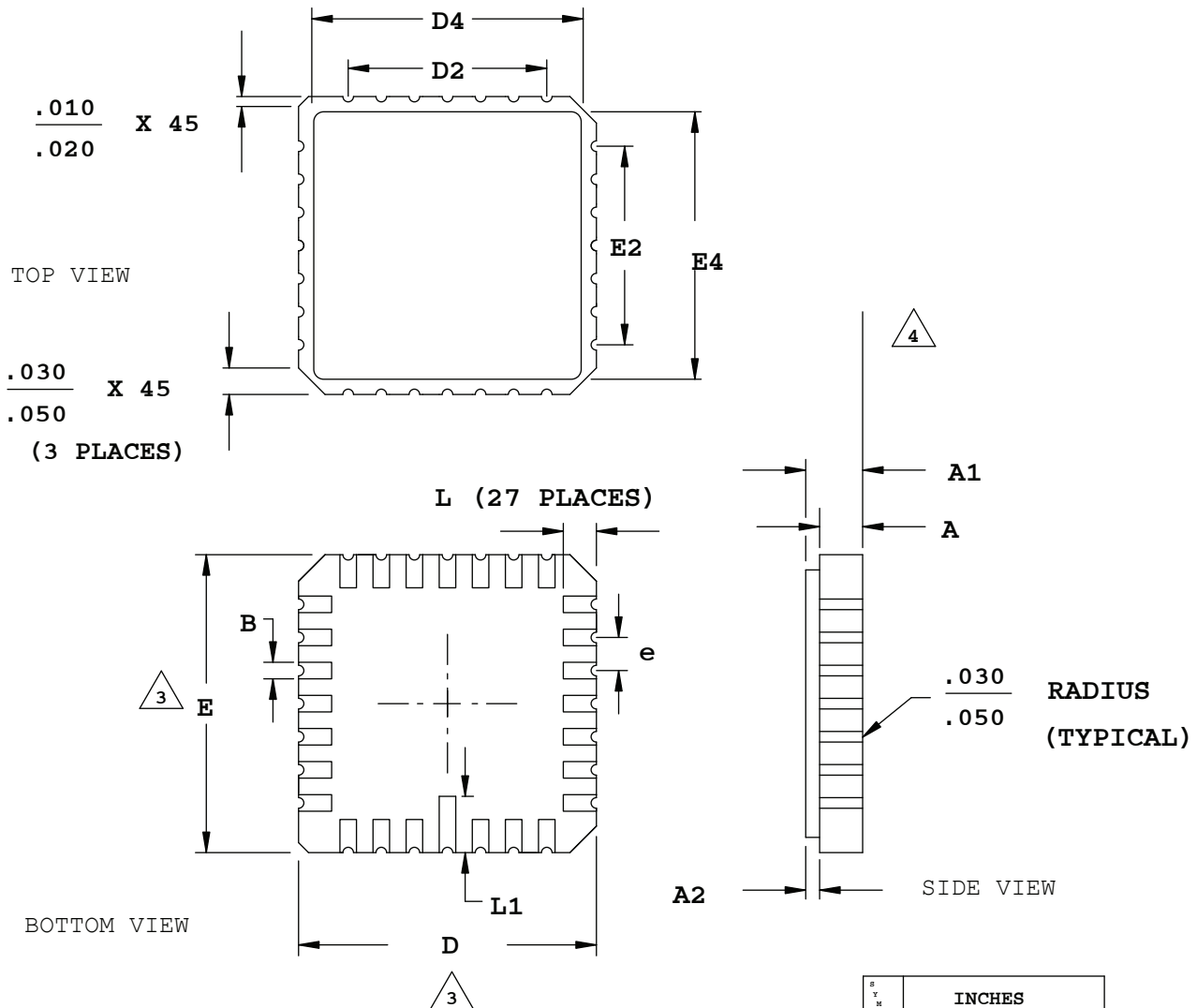
 DIMENSION b APPLIES TO PLATED
TERMINAL AND IS MEASURED BETWEEN
0.15 AND 0.30 mm FROM TERMINAL TIP.

6 APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3	0.2 REF		
D	4.0 BSC		
D2	1.05	-	2.45
E	4.0 BSC		
E2	1.05	-	2.45
b	0.18	0.25	0.30
e	0.50 BSC		
L	0.45	0.50	0.55

28-Pin LCC Package

Dimensions in Inches



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5.
2. ALL DIMENSIONS ARE IN INCHES.

3. DIMENSIONS D AND E MAY HAVE MATERIAL PROTRUSION OF .010 INCHES MAXIMUM ABOVE THE DIMENSION SHOWN NOT TO EXCEED .005 INCHES MAXIMUM PER SIDE.

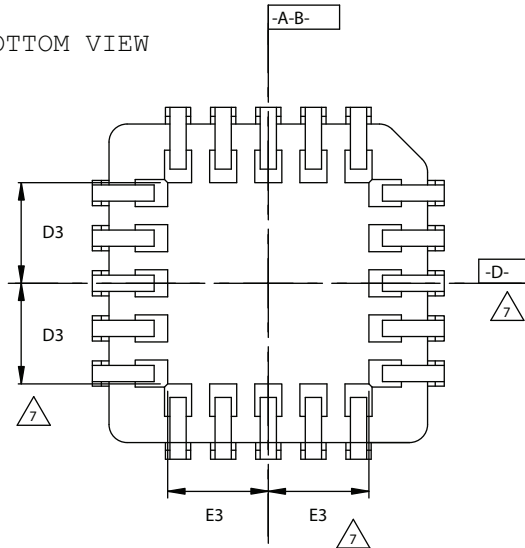
4. FLATNESS TOLERANCE IS .004 INCHES PER INCH.

SYMBOL	INCHES		
	MIN.		MAX.
A	.054		.074
A1	.064		.089
A2	.007		.015
B	.022		.028
D	.440		.460
D2		.300	
D4	.370		.403
E	.440		.460
E2		.300	
E4	.370		.403
e		.050 BSC	
L	.042		.058
L1	.075		.095

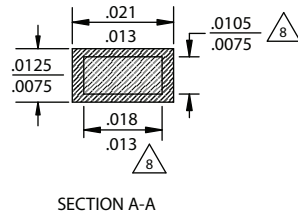
28-Pin PLCC Package

Dimensions in Inches

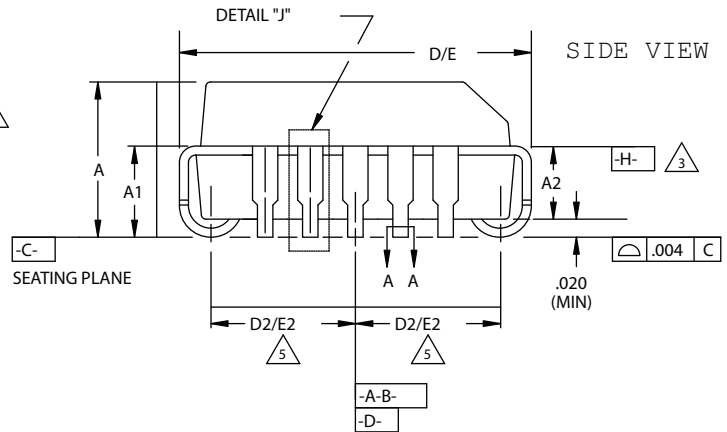
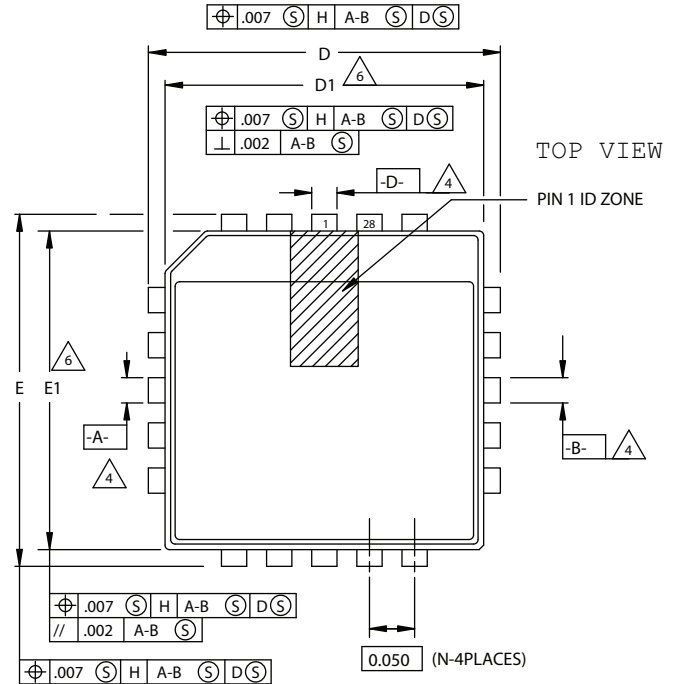
BOTTOM VIEW



SYMBOL	MIN. NOM. MAX.		
	MIN.	NOM.	MAX.
A	.165	.172	.180
A1	.090	.105	.120
A2	.062	-	.083
D	.485	.490	.495
D1	.450	.453	.456
D2	.191	.205	.219
D3		.125	
E	.485	.490	.495
E1	.450	.453	.456
E2	.191	.205	.219
E3		.125	
N		28	

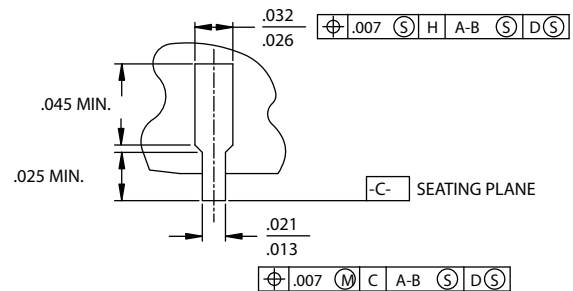


SECTION A-A



NOTES:

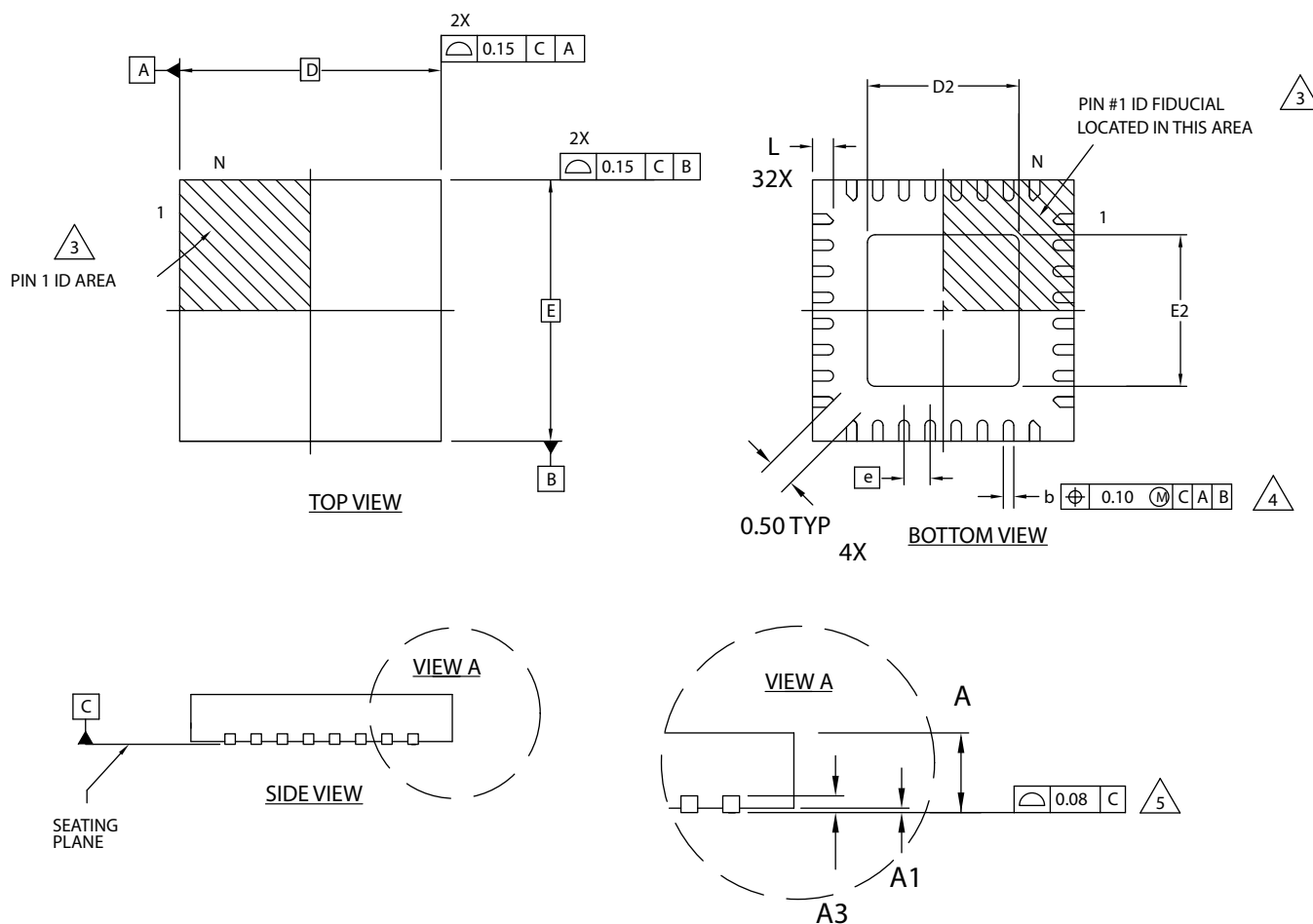
- ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1982
- ALL DIMENSIONS IN INCHES
- DATUM PLANE H- LOCATED AT TOP OF MOLD PARTING LINE AND COINCIDENT WITH TOP OF LEAD WHERE LEAD EXITS PLASTIC BODY
- DATUMS A-B AND D- TO BE DETERMINED WHERE CENTER LEADS EXIT PLASTIC BODY AT DATUM PLANE H-
- TO BE MEASURED AT SEATING PLANE C- CONTACT POINT
- DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .010 PER SIDE.
- TOP POINT OF MEASUREMENT IS DATUM H- ; BOTTOM POINT OF MEASUREMENT IS AT MAJOR FLAT AREA OF LOWER PLASTIC SURFACE DEFINED BY D3/E3
- DIMENSION APPLIES TO BASE METAL ONLY



DETAIL "J" (TYP ALL SIDES)


32-Pin QFN Package Option 1: Power Manager II, iCE40™


Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES
PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

 EXACT SHAPE AND SIZE OF THIS
FEATURE IS OPTIONAL.

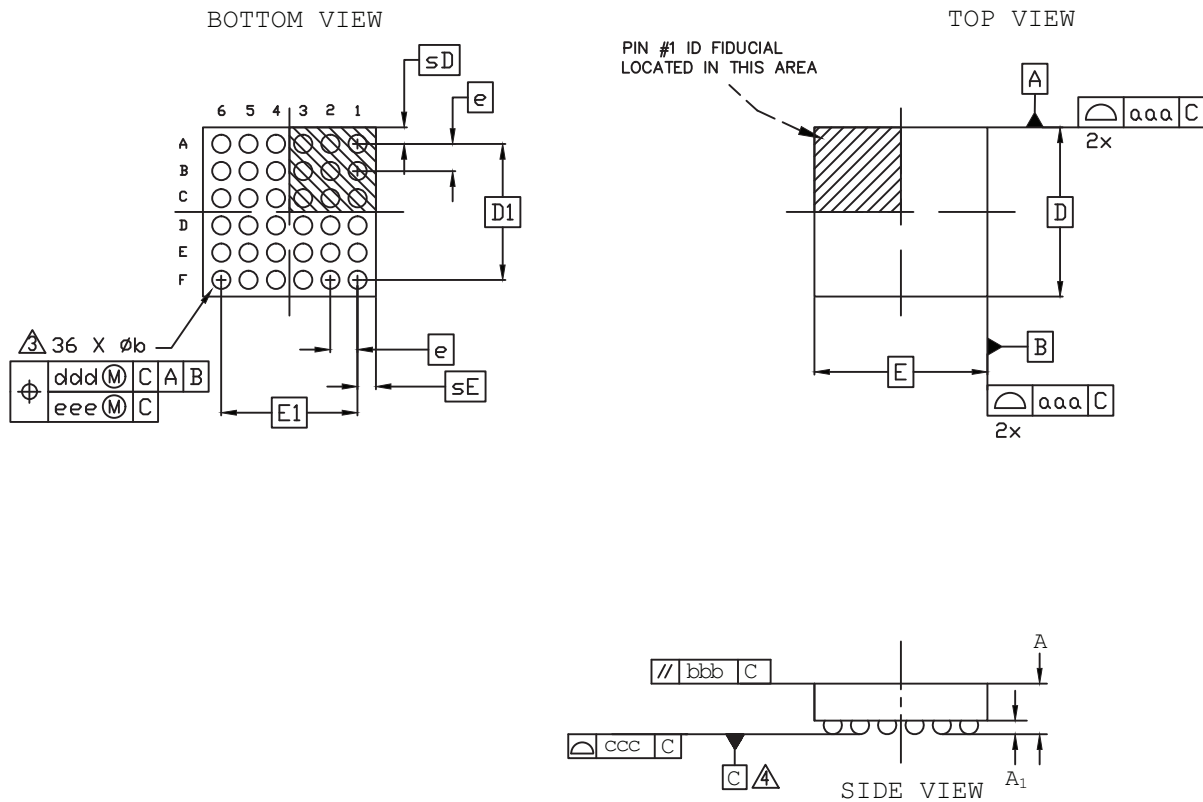
 DIMENSION b APPLIES TO PLATED
TERMINAL AND IS MEASURED BETWEEN
0.15 AND 0.30 mm FROM TERMINAL TIP.

5 APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3	0.2 REF		
D	5.0 BSC		
D2	1.25	2.70	3.75
E	5.0 BSC		
E2	1.25	2.70	3.75
b	0.18	0.24	0.30
e	0.50 BSC		
L	0.30	0.40	0.50

36-Ball WLCS Package Option 2: MachXO3™

Dimensions in Millimeters



NOTES:

1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M - 1994.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

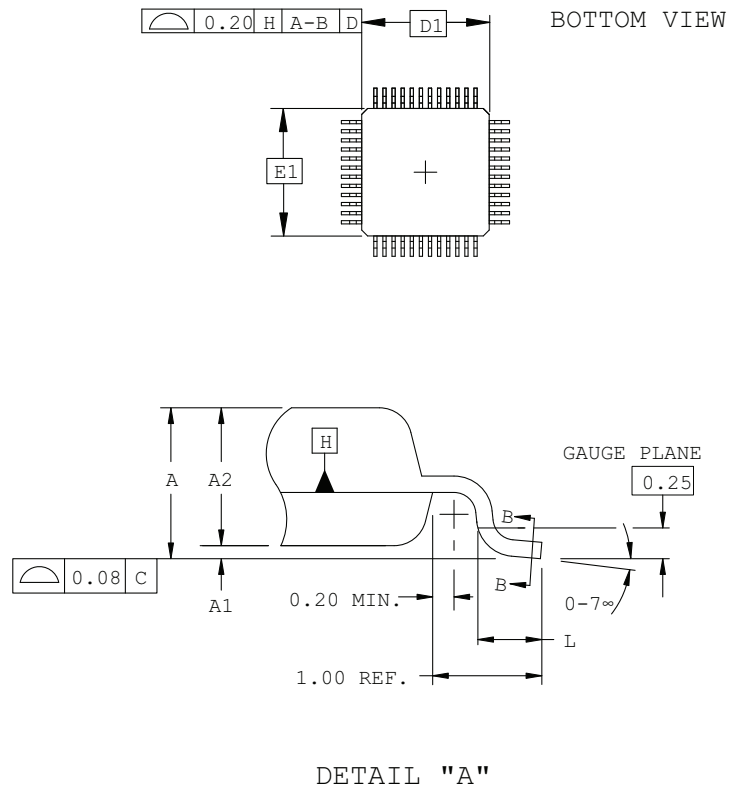
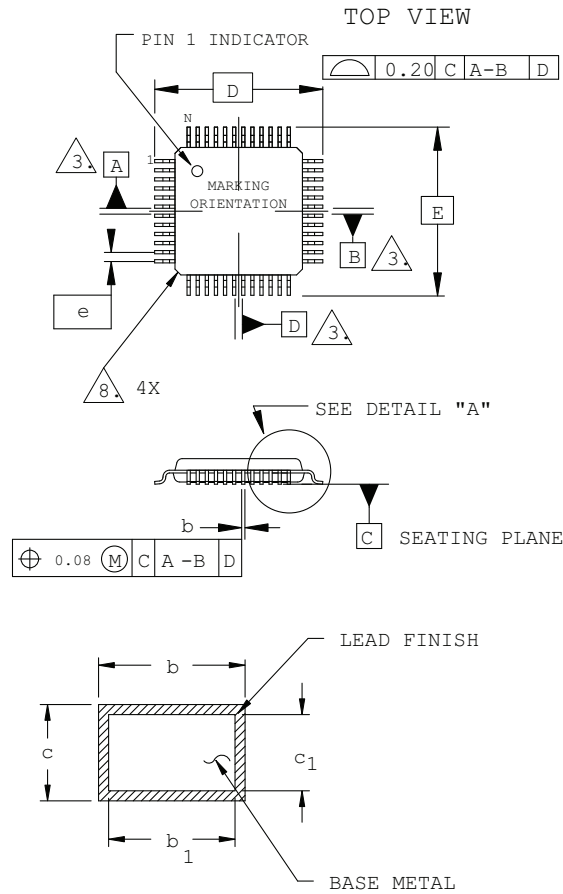
△ DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM [C].

△ PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.

REF.	Min.	Nom.	Max.
A	0.510	0.543	0.576
A1	0.167	0.196	0.225
b	0.239	0.266	0.319
D	2.487 BSC		
E	2.541 BSC		
D1	2.00 BSC		
E1	2.00 BSC		
e	0.40 BSC		
sD	-	0.244	-
sE	-	0.271	-
aaa	0.025		
bbb	0.060		
ccc	0.030		
ddd	0.0150		
eee	0.050		

48-Pin TQFP Package (1.4 mm thick)

Dimensions in Millimeters



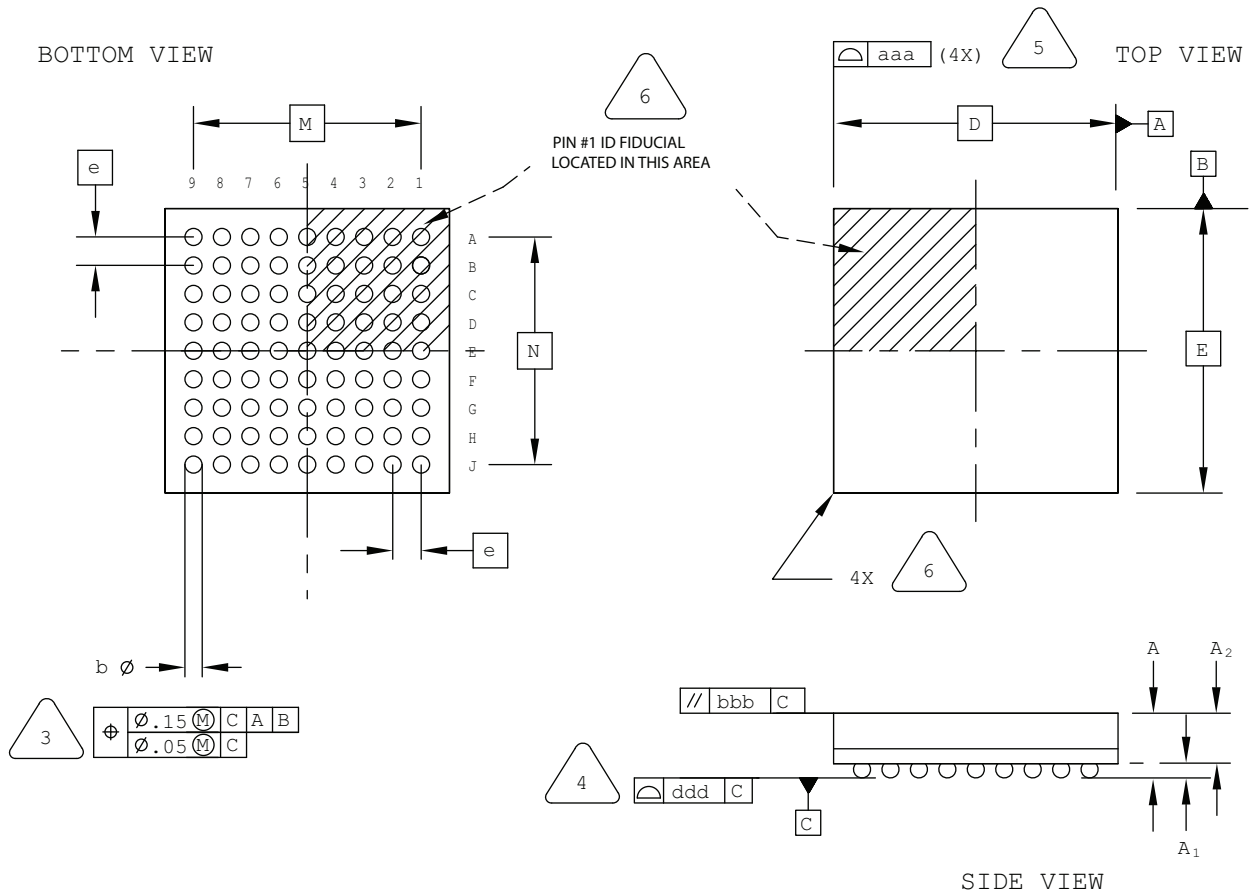
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- SECTION B-B:
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D	9.00 BSC		
D1	7.00 BSC		
E	9.00 BSC		
E1	7.00 BSC		
L	0.45	0.60	0.75
N	48		
e	0.50 BSC		
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
c	0.09	0.15	0.20
c1	0.09	0.13	0.16

81-Ball ucBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

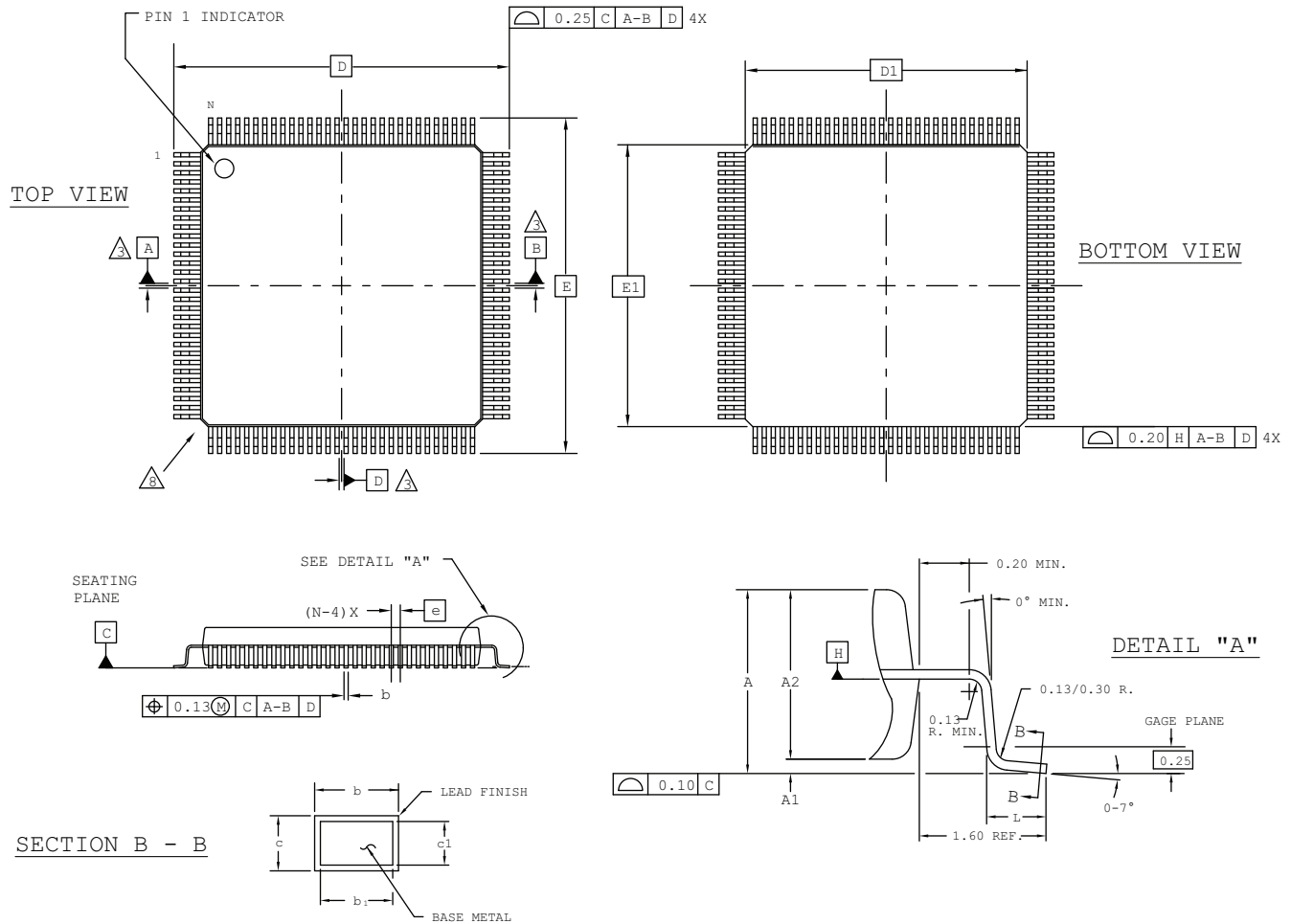


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.10	-	-
A2	-	-	0.90
D/E	4.00 BSC		
M/N	3.20 BSC		
b	0.20	0.25	0.30
e	0.40 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.10

160-Pin PQFP Package

Dimensions in Millimeters



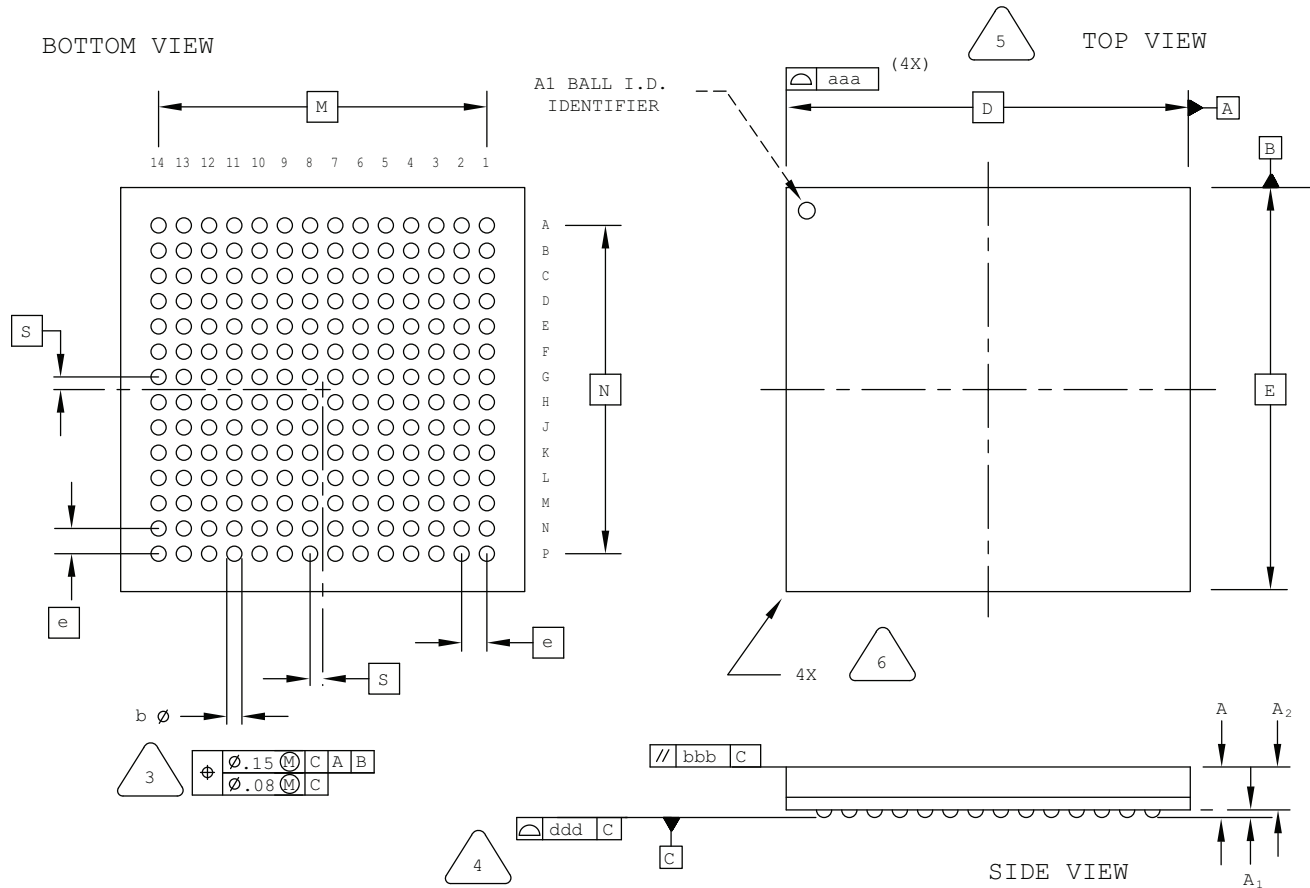
NOTES:

- 1.0 DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
- 2.0 ALL DIMENSIONS ARE IN MILLIMETERS.
- 3.0 DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- 4.0 DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5.0 THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6.0 SECTION B-B:
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7.0 A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- 8.0 EXACT SHAPE OF EACH CORNER IS OPTIONAL.
- 9.0 EXACT SHAPE OF EXPOSED HEATSINK IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	4.10
A1	0.25	-	0.50
A2	3.20	3.40	3.60
D	31.20 BSC		
D1	28.00 BSC		
E	31.20 BSC		
E1	28.00 BSC		
L	0.73	0.88	1.03
N	160		
e	0.65 BSC		
b	0.22	-	0.40
b1	0.22	0.30	0.36
c	0.11	-	0.23
c1	0.11	0.15	0.19

196-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

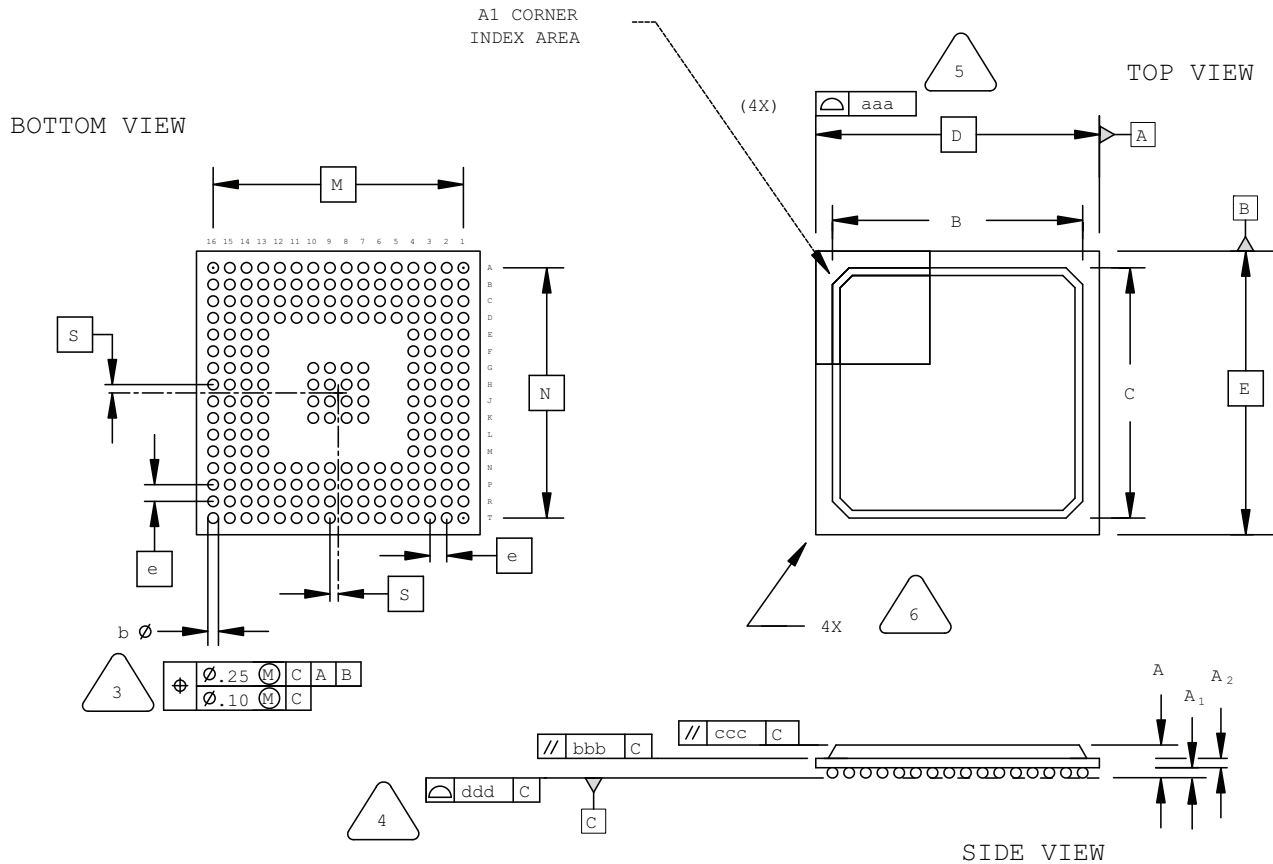


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.15	-	-
A2	-	-	0.85
D/E	8.00 BSC		
M/N	6.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08

208-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

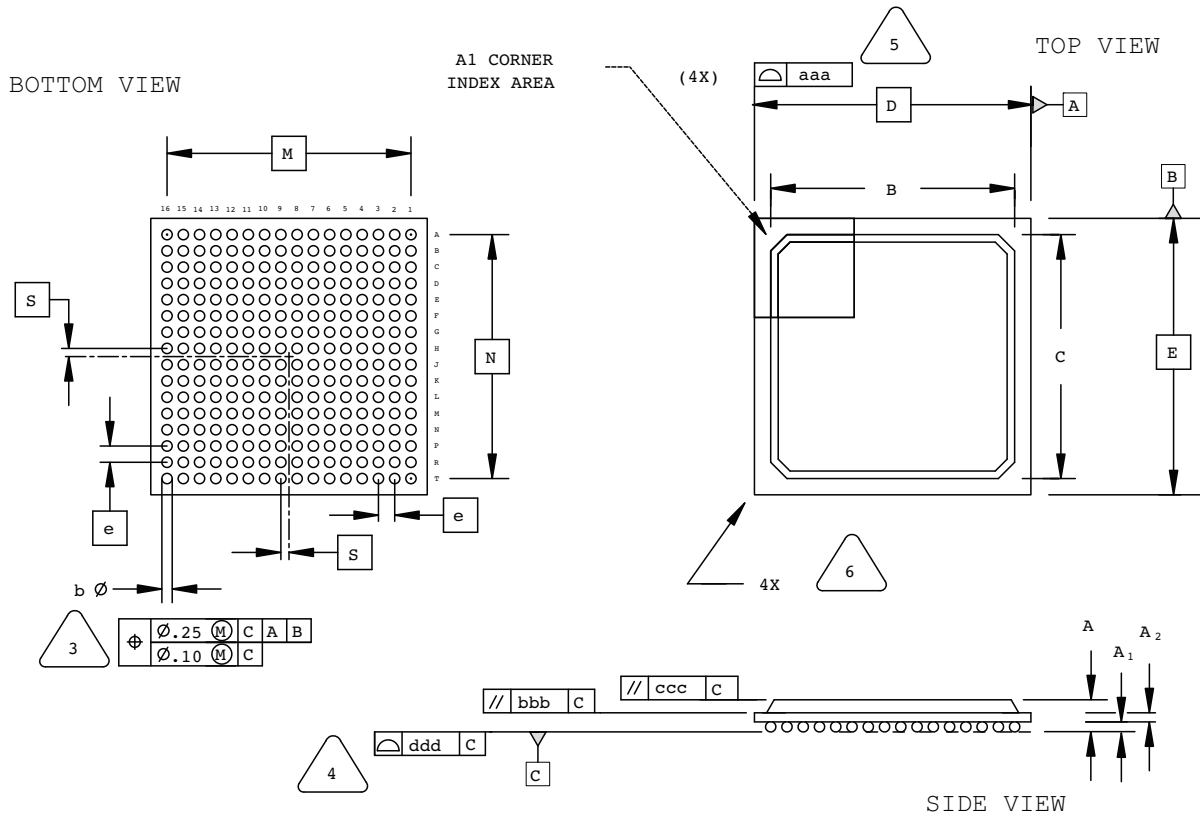


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.70	2.10
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	14.80	15.30	15.80
D/E	17.00 BSC		
M/N	15.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

256-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.70	2.10
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	14.80	15.30	15.80
D/E	17.00 BSC		
M/N	15.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

Dimensions in Millimeters

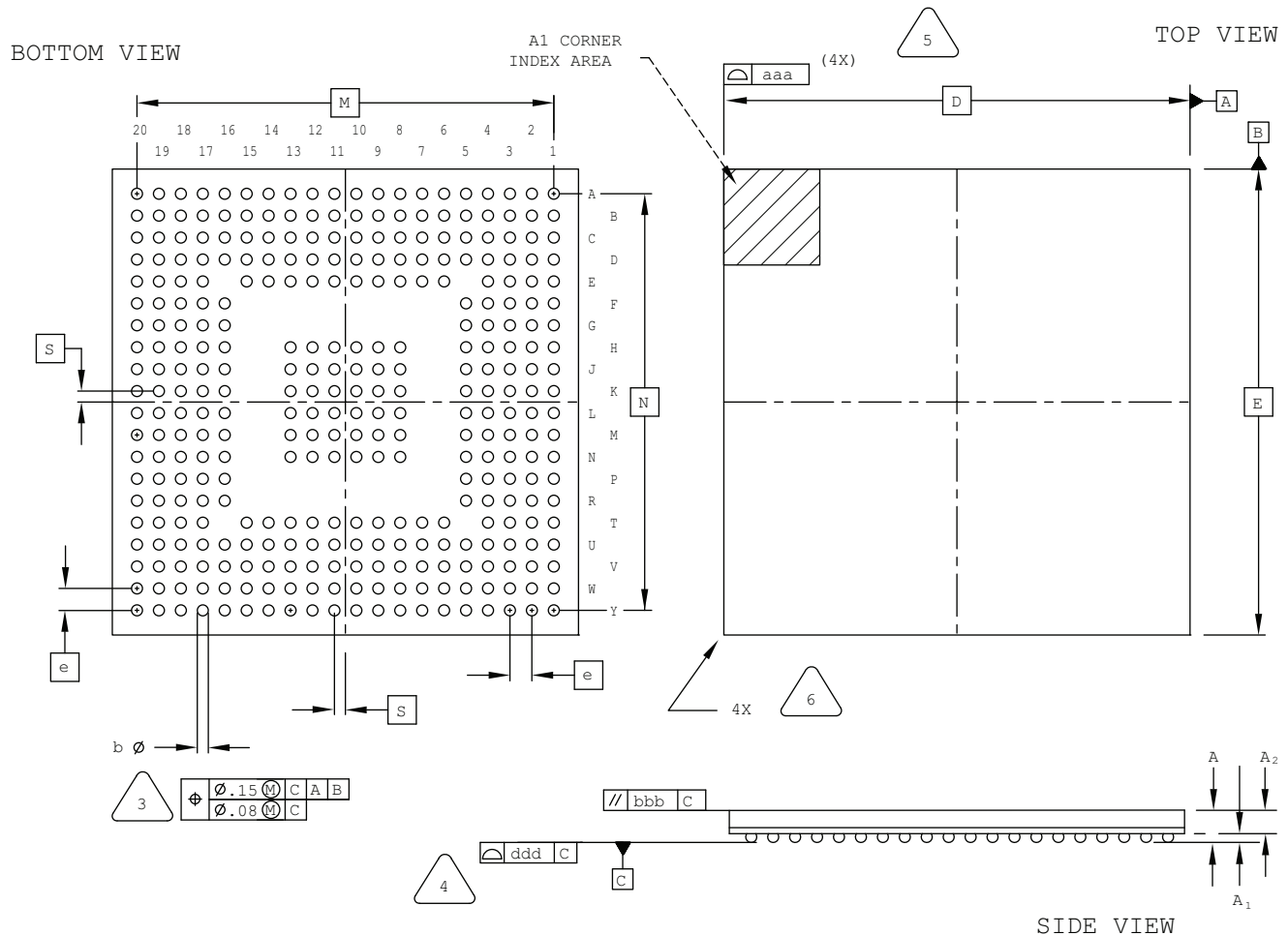


- 3
- DIMENSION "b" IS MEASURED AT THE
MAXIMUM SOLDER BALL DIAMETER,
PARALLEL TO PRIMARY DATUM [C]
- 4
- PRIMARY DATUM [C] AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.
- 5
- BILATERAL TOLERANCE ZONE IS APPLIED
TO EACH SIDE OF THE PACKAGE BODY.
- 6
- EXACT SHAPE AND SIZE OF THIS FEATURE
IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.25	1.50	1.70
A1	0.30	-	-
A2	-	-	1.40
D/E	19.0 BSC		
M/N	17.0 BSC		
S	0.50 BSC		
b	0.40	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20

332-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

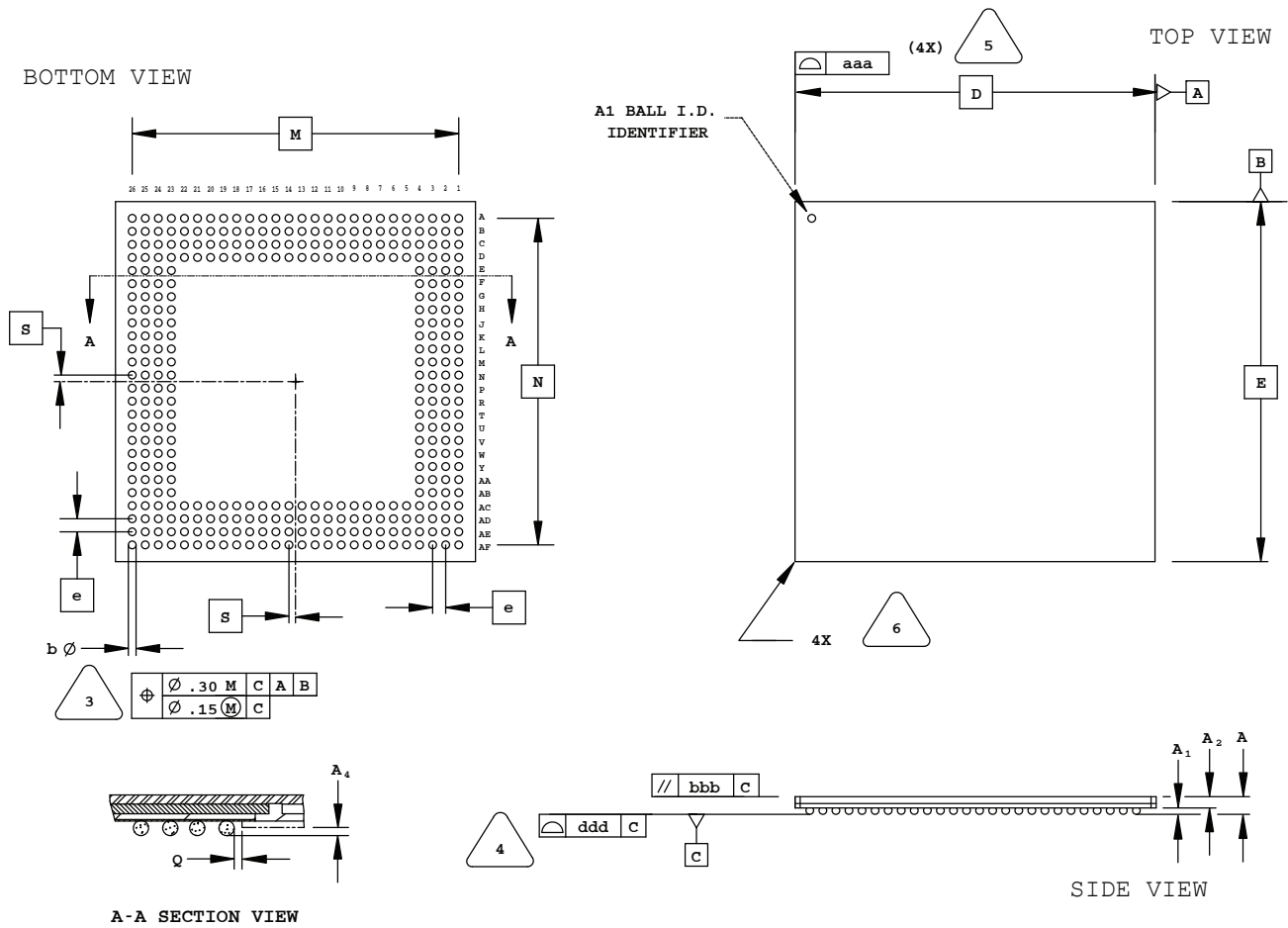
1. DIMENSIONS AND TOLERANCES
PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

- 3
- DIMENSION "b" IS MEASURED AT THE
MAXIMUM SOLDER BALL DIAMETER,
PARALLEL TO PRIMARY DATUM [C]
- 4
- PRIMARY DATUM [C] AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.
- 5
- BILATERAL TOLERANCE ZONE IS APPLIED
TO EACH SIDE OF THE PACKAGE BODY.
- 6
- EXACT SHAPE AND SIZE OF THIS FEATURE
IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	—	—	2.00
A1	0.25	—	—
A2	0.65	—	—
D/E	17.0 BSC		
M/N	15.2 BSC		
S	0.40 BSC		
b	0.40	0.45	0.50
e	0.80 BSC		
aaa	—	—	0.15
bbb	—	—	0.20
ddd	—	—	0.20

352-Ball SBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM **C**



PRIMARY DATUM **C** AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

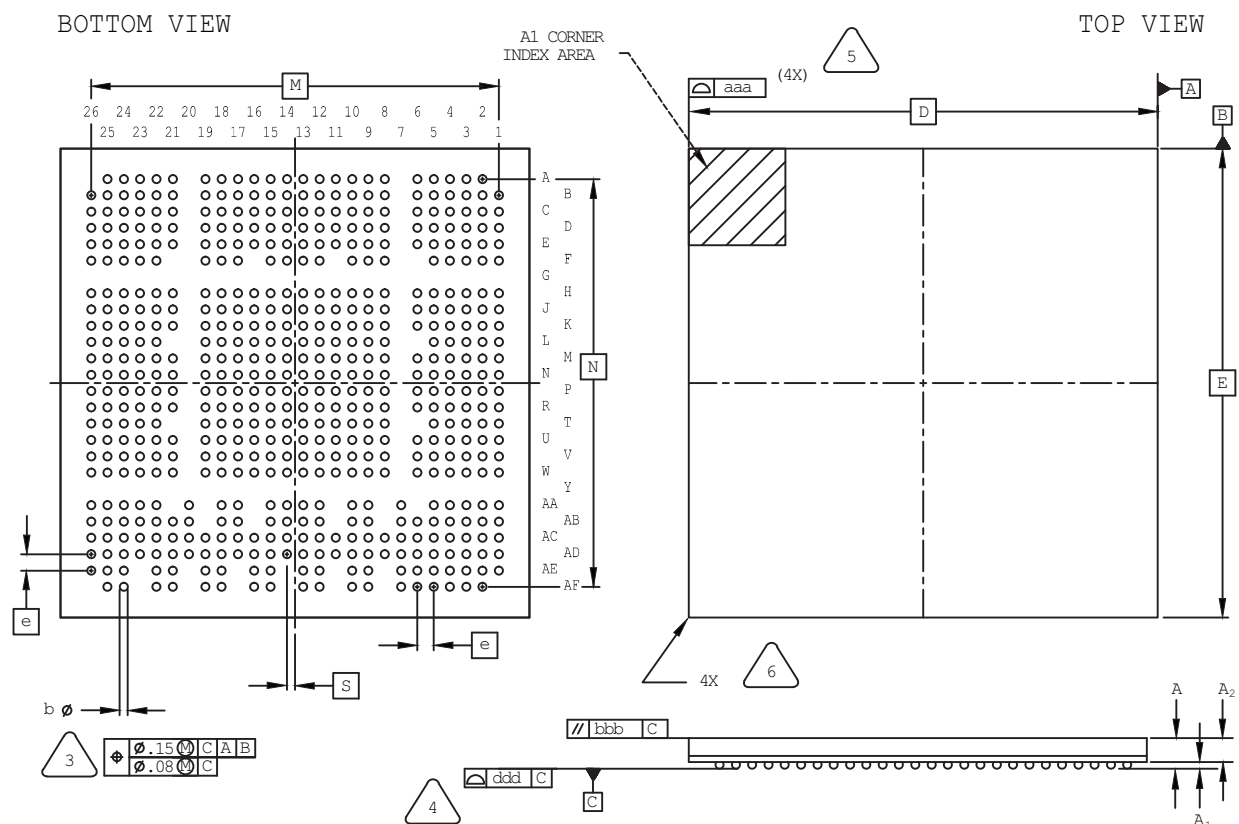


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.50	0.65	0.80
A2	0.80	0.90	1.00
D/E	35.00 BSC		
M/N	31.75 BSC		
S	0.635 BSC		
b	0.60	0.75	0.90
e	1.27 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20

554-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

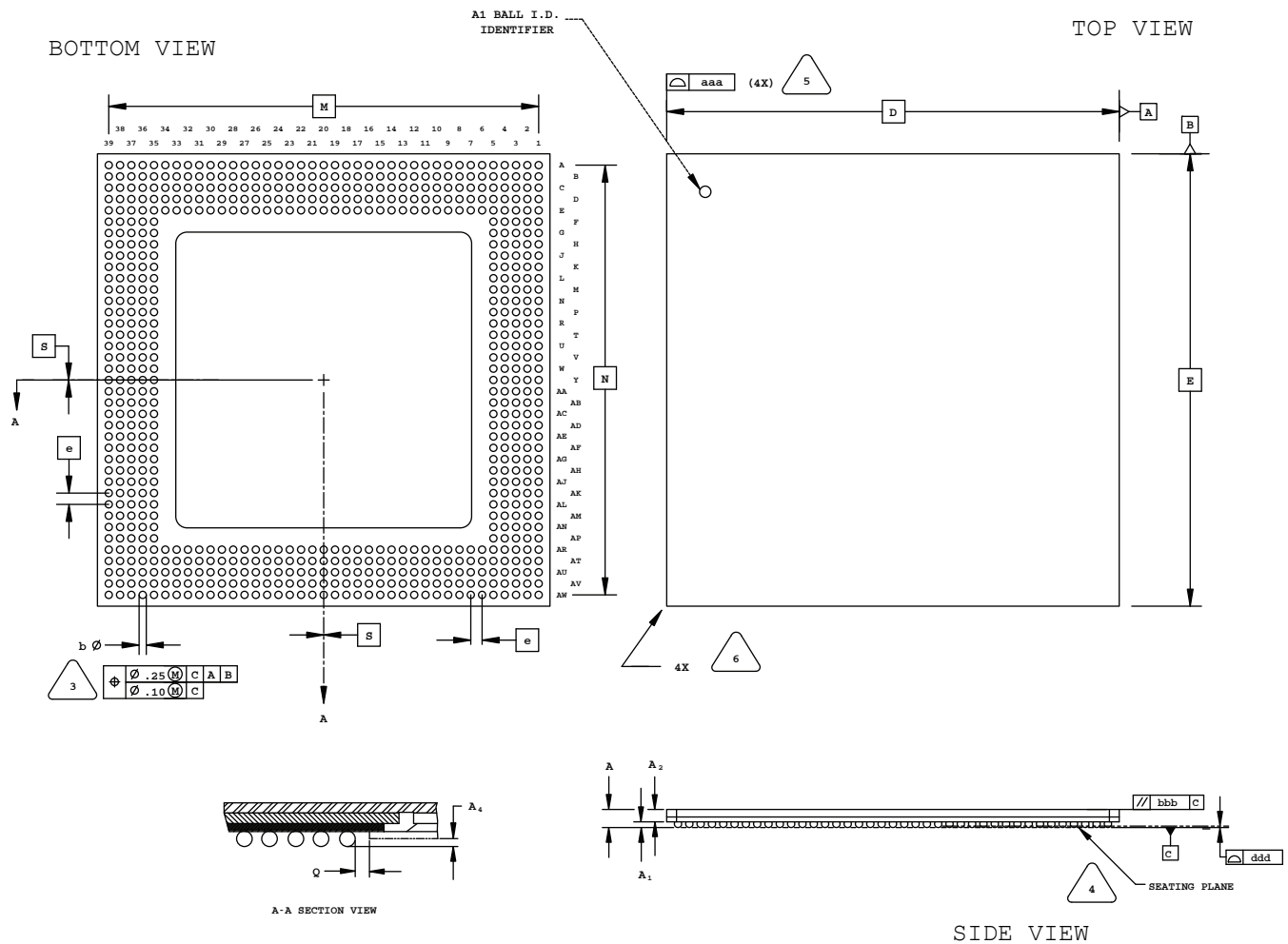
1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

- 3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].
- 4. PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- 6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.76
A1	0.25	0.30	0.35
A2	0.80	-	-
D/E	23.0 BSC		
M/N	20.0 BSC		
S	0.40 BSC		
b	0.35	0.40	0.45
e	0.80 BSC		
aaa	-	-	0.15
bbb	-	-	0.20
ddd	-	-	0.12

680-Ball fpSBGA Package

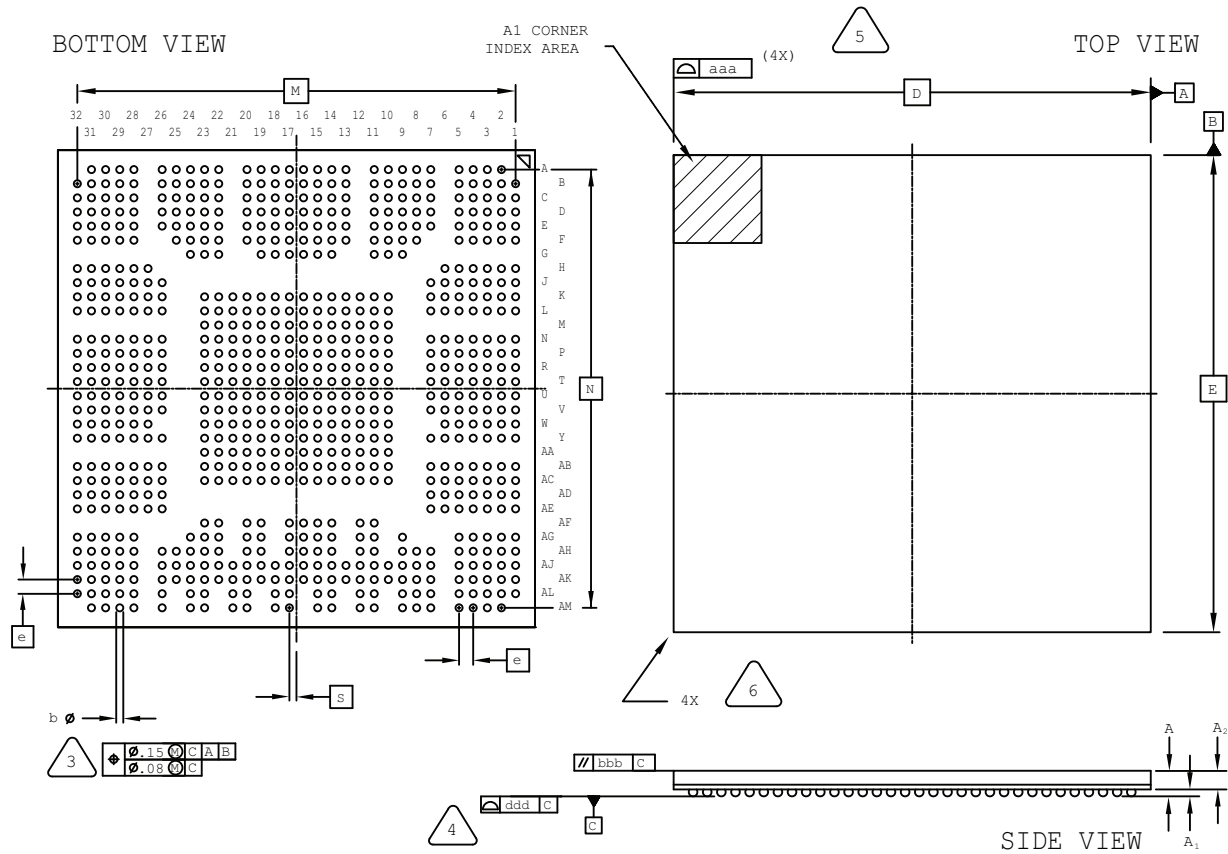
Dimensions in Millimeters



SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.45	0.53	0.60
A2	0.90	0.98	1.05
D/E	40.00 BSC		
M/N	38.00 BSC		
S	0.00 BSC		
b	0.50	0.65	0.80
e	1.00 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20

756-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

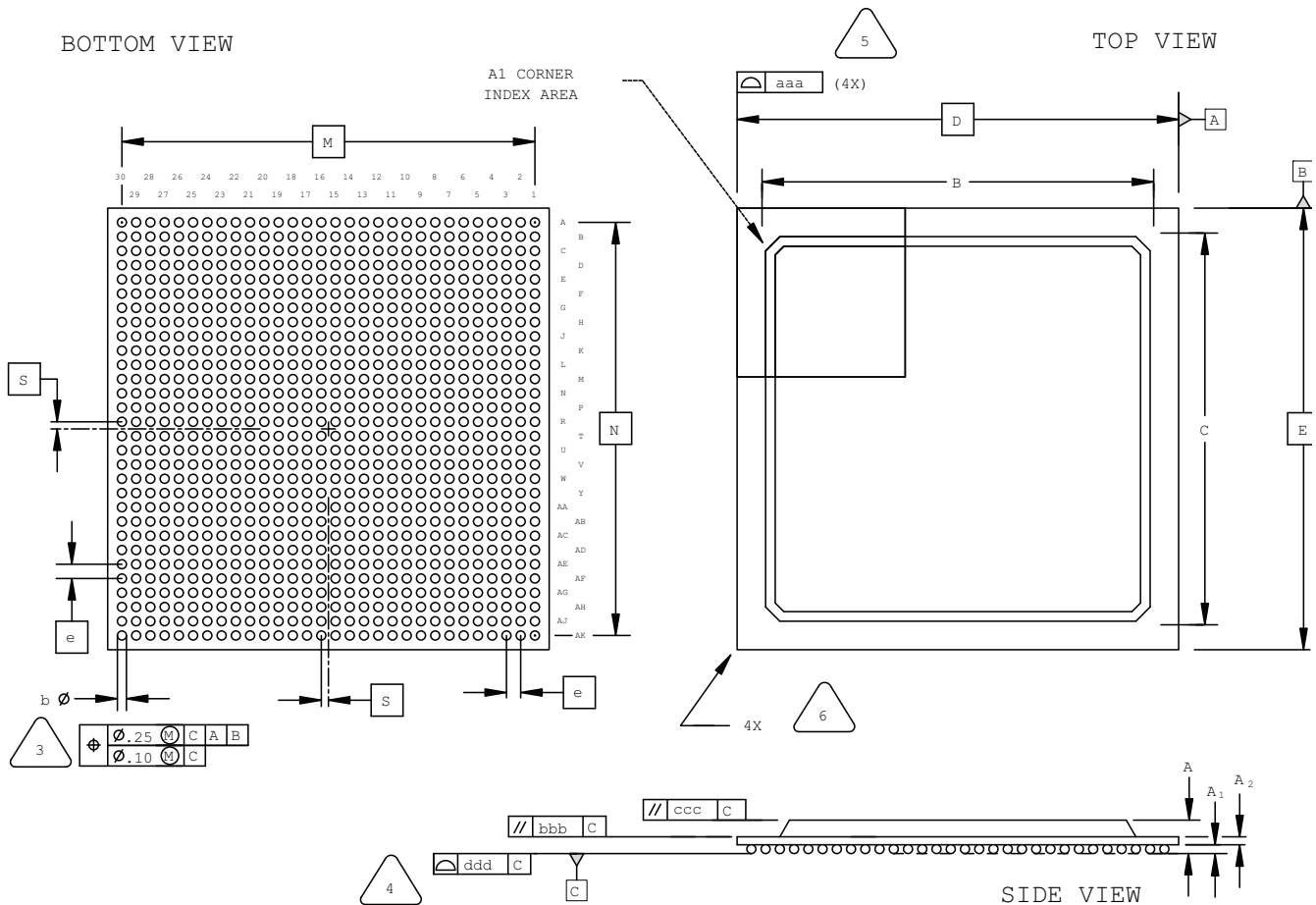
- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.

- 3 DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]
- 4 PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5 BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- 6 EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.76
A1	0.25	0.30	0.35
A2	0.80	-	-
D/E	27.00 BSC		
M/N	24.80 BSC		
S	0.40 BSC		
b	0.35	0.40	0.45
e	0.80 BSC		
aaa	-	-	0.15
bbb	-	-	0.20
ddd	-	-	0.12

900-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM **C**



PRIMARY DATUM **C** AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

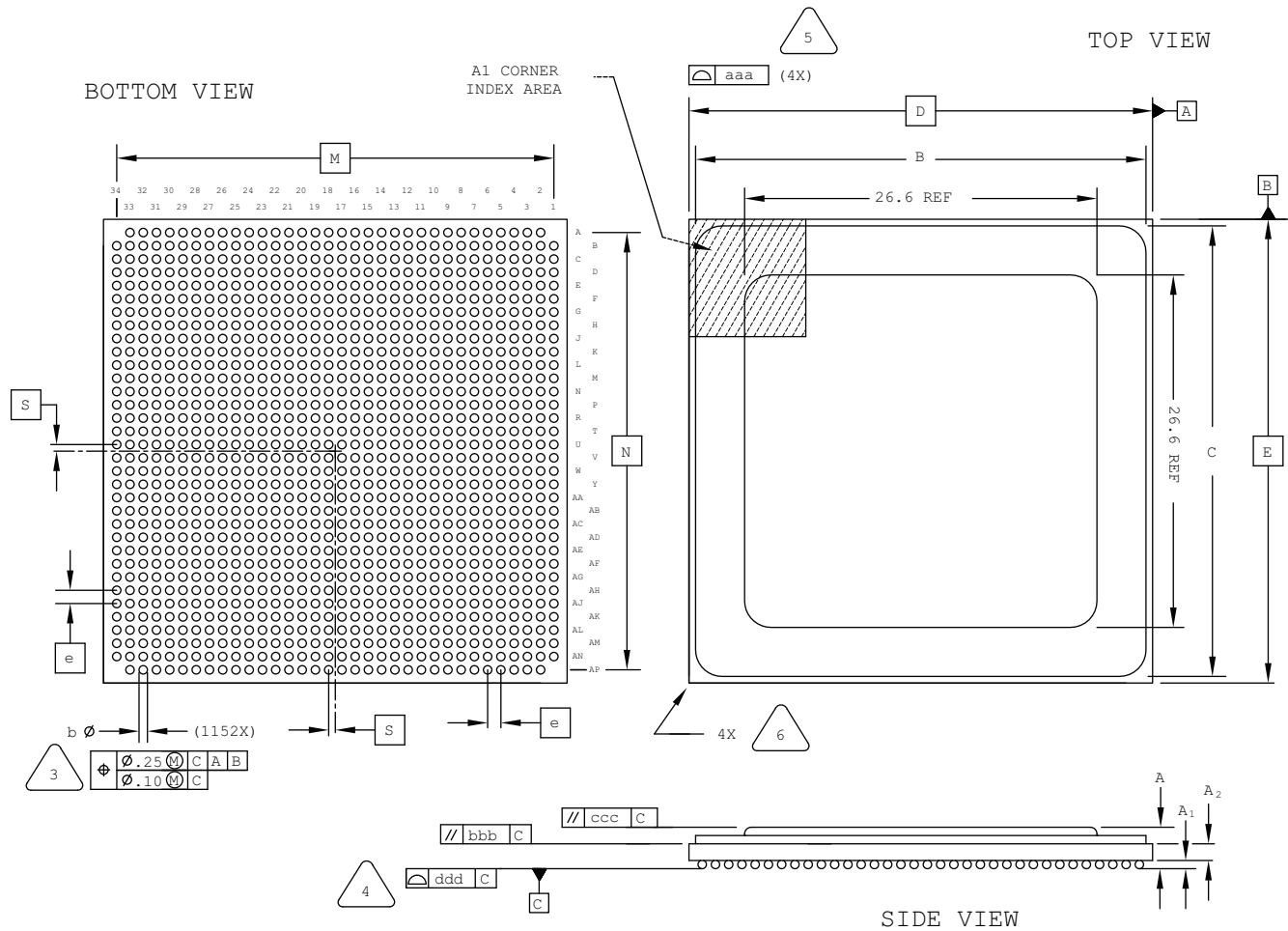


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	25.80	27.55	29.30
D/E	31.00 BSC		
M/N	29.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

1152-Ball Organic fcBGA Package Option 1: LatticeSC/SCM40

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM **C**



PRIMARY DATUM **C** AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



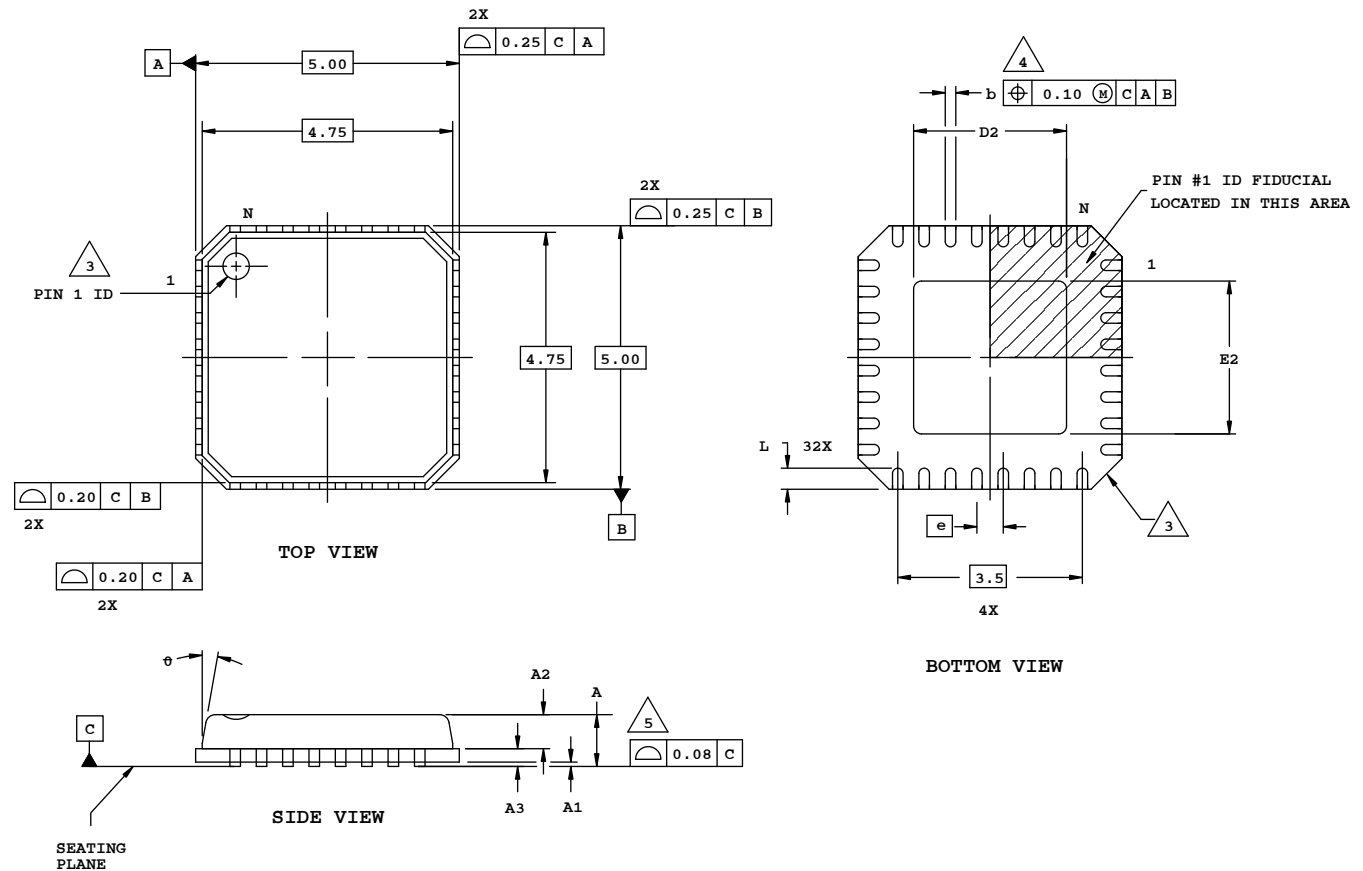
EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	2.55	2.90	3.25
A1	0.35	0.50	0.65
A2	1.20 REF		
B/C	34.25	34.50	34.75
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

Appendix A. Package Archive

32-Pin QFN (Punch Singulated) Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25 mm FROM TERMINAL TIP.

APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
A	-	0.85	1.00
A1	0.00	0.01	0.05
A2	0.00	0.65	1.00
A3	0.20 REF		
D2	1.25	2.70	3.25
E2	1.25	2.70	3.25
e	0.50 BSC		
b	0.18	0.24	0.30
L	0.30	0.40	0.50
θ	-	-	12